Specification of Thermoelectric Module TEC1-12725

Description

The 127 couples, 62 mm × 62 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

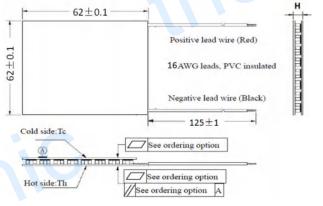
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	16	17.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	22	22	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	220.4	240.8	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	0.56	0.62	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)
	(mm)	Parallelism (mm)	Standard/Optional length
TF	0:4.3±0.1	0:0.12/0.12	125±1/Specify
TF	1:4.3±0.05	1:0.06/0.06	125±1/Specify

Eg. TF00: Thickness 4.3 ± 0.1 (mm) and Flatness 0.12 / 0.12 (mm)

Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217° C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

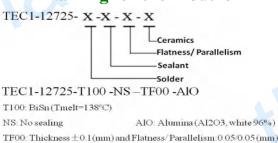
1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

Naming for the Module

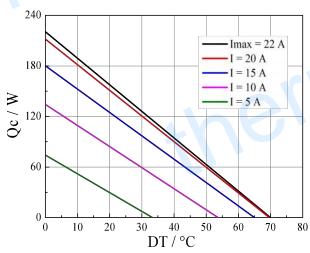


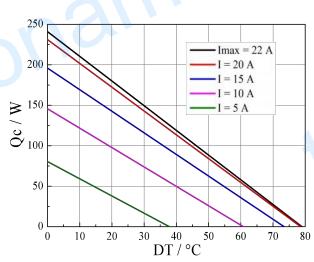
Specification of Thermoelectric Module

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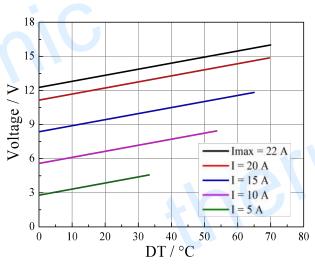
Performance Curves at Th=27 °C

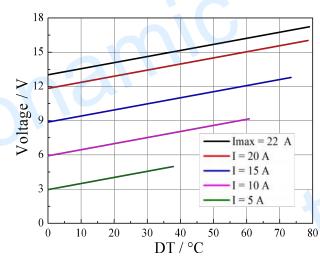
Performance Curves at Th=50 °C



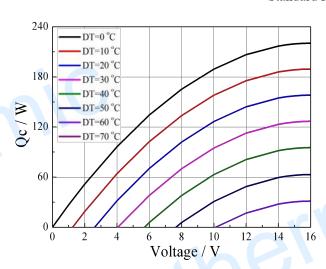


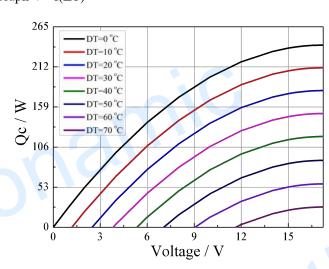
Standard Performance Graph Qc= f(DT)





Standard Performance Graph $V= f(\Delta T)$





Standard Performance Graph Qc = f(V)

0

Specification of Thermoelectric Module

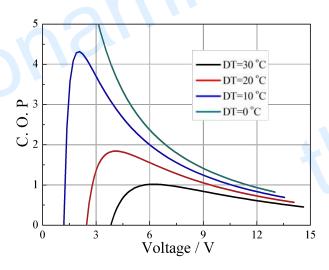
TEC1-12725

Performance Curves at Th=27 °C

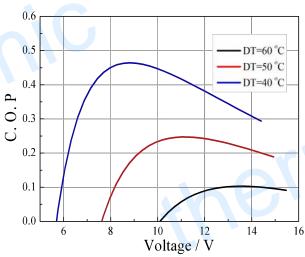
DT=30 °C DT=20 °C DT=10 °C DT=0 °C

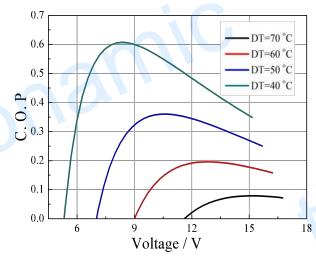
Voltage / V

Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC